MIH Series



- O Low Profile SMD Package
- o **Hermetically Sealed**
- o RoHS Compliant
- o Wide Frequency Range



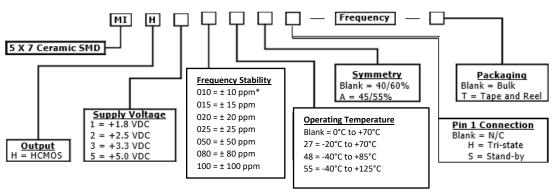
Frequency Range		1.500MHZ to 156.250MHZ			
Temperature Stability*		(See Part Number Guide for Options)			
Operating Temperature Range		(See Part Number Guide for Options)			
Storage Temperature Range		-55°C to +125°C			
Aging (+25°C ±3°C)		±5ppm for first year			
Waveform		HCMOS			
Supply Voltage ±5% (Vdd)	+1.80 VDC	+2.50 VDC	+3.30 VDC	+5.00 VDC	
Supply Current	15mA	40mA	40mA	70mA	
Load	15pF	15pF	10 TTL Gates or 30pF	10 TTL Gates or 50pF	
Logic "0"		10% Vdd max			
Logic "1"		90% Vdd min			
Rise/Fall Time (10% to 90% of Supply Voltage)		4nSec			
Symmetry (50% of waveform)		40%/60% (45%/55% optional)			
Start-up Time		10mSec max			
Jitter (RMS)		Less than 1 pSec			
Tri-State Operation		Vih = 70% of Vdd min to Enable Output Vil = 30% max or grounded to Disable Output (High Impedance)			
Standby Current Consumption		10uA			
* Inclusive of Temperature., Load and Voltage	•				

Mechanical & Environmental Detail

Shock	MIL-STD-883, Method 2002 Cond B	
Solderability	MIL-STD-883, Method 2003	
Solvent Resistance	MIL-STD-202, Method 215	
Vibration	MIL-STD-883, Method 2007, Cond A	
Gross Leak Test	MIL-STD-883, Method 1014, Cond C	
Fine Leak Test	MIL-STD-883, Method 1014, Cond A2	
MSL	Level 1 per IPC/JEDEC J-STD 20	

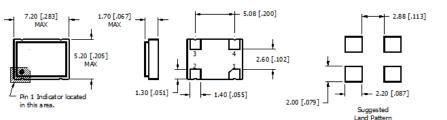


Part Number Guide



Please Consult with MMD Sales Department for any other Parameters or Options

Mechanical Details

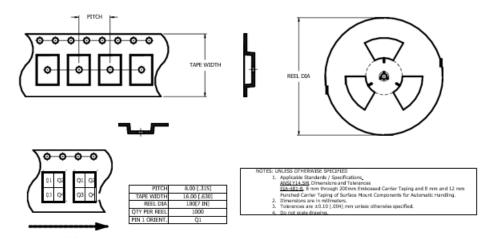


Pin Connections		
Pin 1	N/C, Tri-state or Stand by	
Pin 2	Case Ground	
Pin 3	Output	
Pin 4	Supply Voltage	

- es: Dimensions in brackets are in inches. An External Bypass Capacitor is recommended.

Pads plating
Base or under conductor Ni thickness; 1.3 um to 8.8 um Final plating; Au (99.9%) less than 0.5 um, 0.3 um typ

Tape & Reel Dimensions



^{*}Not available in +1.8 VDC and +2.5 VDC